

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tatsuya INOKUCHI	06/25/2009
Takahisa OHGAMI	06/25/2009
Goh SHIMIZU	06/16/2009
Koichi SOTOYAMA	06/25/2009
Satoshi AIDA	06/16/2009
Shizuka WATANABE	06/16/2009
Yoshinori ICHIKAWA	06/25/2009
Hiroshi KIMURA	06/19/2009

RECEIVING PARTY DATA

Name:	SONY CORPORATION
Street Address:	1-7-1 Konan, Minato-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	108-0075

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12496020

CORRESPONDENCE DATA

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OP \$40.00 12496020

ATTORNEY DOCKET NUMBER:	344587US8
NAME OF SUBMITTER:	Ismail Ahmadi
Total Attachments: 6 source=344587USAssignment#page1.tif source=344587USAssignment#page2.tif source=344587USAssignment#page3.tif source=344587USAssignment#page4.tif source=344587USAssignment#page5.tif source=344587USAssignment#page6.tif	

Docket Number: _____

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in ~~INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING SYSTEM, INFORMATION RECORDING MEDIUM, INFORMATION PROCESSING METHOD, AND PROGRAM~~ for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

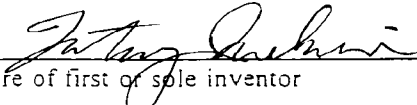
And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

Tatsuya INOKUCHI
Name of first or sole inventor

June 25, 2009
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of first or sole inventor


Signature of first or sole inventor

June 25, 2009
Date of this assignment

Takahisa OHGAMI
Name of second inventor

June 25, 2009
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of second inventor

Takahisa Ohgami
Signature of second inventor

June 25, 2009
Date of this assignment

Goh SHIMIZU
Name of third inventor

June 25, 2009
Execution date of U.S. Patent Application

Tokyo, Japan
Residence of third inventor

Signature of third inventor

Date of this assignment

Koichi SOTOYAMA
Name of fourth inventor

Execution date of U.S. Patent Application

Tokyo, Japan
Residence of fourth inventor

Signature of fourth inventor

Date of this assignment

Satoshi AIDA
Name of fifth inventor

Execution date of U.S. Patent Application

Tokyo, Japan
Residence of fifth inventor

Signature of fifth inventor

Date of this assignment

Shizuka WATANABE
Name of sixth inventor Execution date of U.S. Patent Application
Tokyo, Japan
Residence of sixth inventor

Signature of sixth inventor Date of this assignment

Yoshinori ICHIKAWA
Name of seventh inventor Execution date of U.S. Patent Application
Tokyo, Japan
Residence of seventh inventor

Signature of seventh inventor Date of this assignment

Hiroshi KIMURA
Name of eighth inventor Execution date of U.S. Patent Application
Saitama, Japan
Residence of eighth inventor

Signature of eighth inventor Date of this assignment

Name of ninth inventor Execution date of U.S. Patent Application

Residence of ninth inventor

Signature of ninth inventor Date of this assignment

Docket Number: _____

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in ~~INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING SYSTEM, INFORMATION RECORDING MEDIUM, INFORMATION PROCESSING METHOD, AND PROGRAM~~ for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 1-7-1 Konan, Minato-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: _____, Filing Date: _____.

This assignment executed on the dates indicated below.

<u>Tatsuya INOKUCHI</u>	_____
Name of first or sole inventor	Execution date of U.S. Patent Application
<u>Tokyo, Japan</u>	_____
Residence of first or sole inventor	
_____	_____
Signature of first or sole inventor	Date of this assignment

<u>Takahisa OHGAMI</u>	
Name of second inventor	Execution date of U.S. Patent Application
<u>Tokyo, Japan</u>	
Residence of second inventor	
Signature of second inventor	Date of this assignment

<u>Goh SHIMIZU</u>	<u>June 16, 2009</u>
Name of third inventor	Execution date of U.S. Patent Application
<u>Tokyo, Japan</u>	
Residence of third inventor	
<u>Goh Shimizu</u>	<u>June 16, 2009</u>
Signature of third inventor	Date of this assignment

<u>Koichi SOTOYAMA</u>	<u>June 25, 2009</u>
Name of fourth inventor	Execution date of U.S. Patent Application
<u>Tokyo, Japan</u>	
Residence of fourth inventor	
<u>Koichi Sotoyama</u>	<u>June 25, 2009</u>
Signature of fourth inventor	Date of this assignment

<u>Satoshi AIDA</u>	<u>June 16, 2009</u>
Name of fifth inventor	Execution date of U.S. Patent Application
<u>Tokyo, Japan</u>	
Residence of fifth inventor	
<u>satoshi aida</u>	<u>June 16, 2009</u>
Signature of fifth inventor	Date of this assignment

<u>Shizuka WATANABE</u>	<u>June 16, 2009</u>
Name of sixth inventor	Execution date of U.S. Patent Application
<u>Tokyo, Japan</u>	
Residence of sixth inventor	
<u>Shizuka Watanabe</u>	<u>June 16, 2009</u>
Signature of sixth inventor	Date of this assignment

<u>Yoshinori ICHIKAWA</u>	<u>June 25, 2009</u>
Name of seventh inventor	Execution date of U.S. Patent Application
<u>Tokyo, Japan</u>	
Residence of seventh inventor	
<u>Yoshinori Ichikawa</u>	<u>June 25, 2009</u>
Signature of seventh inventor	Date of this assignment

<u>Hiroshi KIMURA</u>	<u>June 19, 2009</u>
Name of eighth inventor	Execution date of U.S. Patent Application
<u>Saitama, Japan</u>	
Residence of eighth inventor	
<u>Hiroshi Kimura</u>	<u>June 19, 2009</u>
Signature of eighth inventor	Date of this assignment

Name of ninth inventor	Execution date of U.S. Patent Application
Residence of ninth inventor	
Signature of ninth inventor	Date of this assignment

PATENT

RECORDED: 07/01/2009

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